PCN Number:	20160107000		PCN Date:	1/12/2016
Title:	Datasheet for LMK0482x			
Customer Contact:	PCN Manager		**Dept:**	Quality Services
Change Type:				

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification etc.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.

TEXAS INSTRUMENTS

LMK04821, LMK04826, LMK04828

SNAS605AR –MARCH 2013–REVISED DECEMBER 2015

Changes from Revision AQ (August 2014) to Revision AR   **Page**

Device Family	Change From:	Change To:
LMK0482x	SNAS605AQ	**SNAS605AR**

These changes may be reviewed at the datasheet links provided.
http://www.ti.com/product/LMK04828

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

LMK04821NKDR	LMK04826BISQ/NOPB	LMK04826BISQX/NOPB	LMK04828BISQE/NOPB
LMK04821NKDT	LMK04826BISQE/NOPB	LMK04828BISQ/NOPB	LMK04828BISQX/NOPB

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com